1. A method of coating solder ball and wire bond bond pads comprising:

masking said solder ball bond pads; and

coating gold on said wire bond bond pads with said solder ball bond pads masked.

2. The method of claim 1 including providing a different gold coating thickness on said solder ball bond pads and said wire bond bond pads.

3. The method of claim 2 including providing a thicker gold coating on said wire bond bond pads than on said solder ball bond pads.

4. The method of claim 3 including providing a gold coating, on said wire bond bond pads, having a thickness of about .5 microns and providing a solder ball bond pad gold coating of approximately .1 to .3 microns in thickness.

5. The method of claim 1 including nickel coating said solder ball and said wire bond bond pads at the same time before coating said wire bond bond pads with gold.

6. The method of claim 1 including coating said wire bond bond pads with a first gold coating and coating both

of said solder ball bond pads and said wire bond bond pads with a second gold coating.

7. The method of claim 6 wherein said second gold coating is thinner than said first gold coating.

8. The method of claim 1 including using an electroless plating technique to coat gold on said wire bond bond pads.

9. The method of claim 1 including forming a laminate structure having solder ball bond pads and wire bond bond pads on the same surface.

10. The method of claim 1 wherein said solder ball bond pads are gold coated in a single step.

11. The method of claim 10 including coating said solder ball bond pads and said wire bond bond pads while the other of said solder ball and wire bond bond pads is masked.

12. A method of coating two different types of bond pads on the same surface comprising:

masking off a first type of bond pad; and

coating a metal on the second type of bond pad with said first type of bond pad being masked.

13. The method of claim 12 including masking solder ball bond pads.

14. The method of claim 13 including coating metal on wire bond bond pads.

15. The method of claim 14 including coating gold on said wire bond bond pads.

16. The method of claim 15 including unmasking said solder ball bond pads and coating a metal on both said wire bond bond pads and said solder ball bond pads.

17. The method of claim 12 including providing different coating thicknesses on said first and second types of bond pads.

18. The method of claim 12 including coating gold on said second type of bond pad.

19. The method of claim 18 wherein said first type of bond pad is a solder ball bond pad and said second type of bond pad is a wire bond bond pad, coating gold on said wire

bond bond pad to a thickness of about .5 microns and coating gold on said solder ball bond pads to a thickness of about .1 to about .3 microns.

20. The method of claim 19 including nickel coating said first and second types of bond pads at the same time before coating said wire bond bond pads with said metal.

21. The method of claim 12 including coating both said first and second types of bond pads with said metal after coating said metal on said second type of bond pad.

22. The method of claim 12 including masking off said second type of bond pad and coating metal on said first type of bond pad.

23. A method of forming solder ball and wire bond bond pads comprising:

forming a solder ball bond pad;

coating gold over said solder ball bond pad;

forming a wire bond bond pad; and

coating gold over said wire bond bond pad to a thickness greater than said gold coating over said solder ball bond pad.

24. The method of claim 23 including masking said solder ball bond pad and coating gold on said wire bond bond pad with said solder ball bond pad masked.

25. The method of claim 24 including providing a gold coating on said wire bond bond pad having a thickness of about .5 microns.

26. The method of claim 23 including providing a gold coating on said solder ball bond pad of approximately .1 to .3 microns in thickness.

27. The method of claim 23 including coating said wire bond bond pads with a first gold coating and coating both of said solder ball and said wire bond bond pads with a second gold coating.

28. The method of claim 23 including coating said solder ball bond pad to a thickness of approximately .25 microns.

29. A method of forming solder ball and wire bond bond pads comprising:

masking said solder ball bond pad;

coating gold over said wire bond bond pad;

masking said wire bond bond pad; and

coating gold over said solder ball bond pad.

30. The method of claim 29 including coating said wire bond bond pad with gold to a thickness greater than the gold coating over said solder ball bond pad.

31. A packaged integrated circuit device comprising:

a plurality of gold coated solder ball bond pads;

a plurality of gold coated wire bond bond pads; and

the gold coating on said solder ball bond pads being thinner than the gold coating on said wire bond bond pads.

32. The device of claim 31 wherein the thickness of the gold on said solder ball bond pads is sufficiently low to reduce the likelihood of solder ball joint embrittlement.

33. The device of claim 31 wherein said solder ball bond pads have a gold coating having a thickness of between about .1 and .3 microns.

34. The device of claim 33 wherein said solder ball bond pad gold coating has a thickness of about .25 microns.

35. The device of claim 33 wherein said wire bond bond pads have a gold coating thickness of approximately .5 microns.

36. The device of claim 31 wherein said solder ball bond pads and said wire bond bond pads are all contained on the same planar surface.